ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC Bannockl	burn Illinois. A	ll rights reserved nations.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute					ials and M	als and Mfg Information				
upplier Information														
Company name*		Company uni	Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi										2024-05	2024-05-02			
ntact Name Title - Contact			et		Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards Product En			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			epresentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	lanufacturing Site		Weight*	UOM	Unit Type	
	NSVP26	NSVP264SDSF3T1G PIN-DIODE		DE 50V 50mA		2024-05-02		C	CNG		6.52	mg	Each	
Ianufacturing Proccess Informa	tion						-	·						
Terminal Plating / Grid Array Ma	aterial	Ferminal Base A	Alloy J-STD-020 MSL Rat		L Rating	Peak Proce	ak Process Body Temperatu		ure Max Time at Peak Temper		ture Num	ber of Reflow Cyc	cles	
contains Bi CU Alloy		CU Alloy		1		260		С	30	secor	nds 3			
omments														
vel 1 - maximum time at peak temperatu	ire during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Lead Frame	2.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0875	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0051	mg
			Supplier	Iron (Fe)	7439-89-6		0.0678	mg
			Supplier	Copper (Cu)	7440-50-8		2.5358	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0038	mg
Mold Compound-Black	3.55	mg	Supplier	Carbon Black (C)	1333-86-4		0.011	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.2705	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.6863	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.5467	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0355	mg
Plating	0.16	mg	В	Bismuth (Bi)	7440-69-9		0.001	mg
			Supplier	Tin (Sn)	7440-31-5		0.159	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg